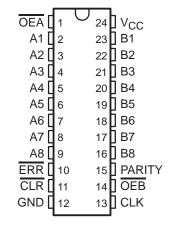
- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- High-Drive Outputs (-32-mA IOH, 64-mA IOI)
- **Parity Error Flag With Parity** Generator/Checker
- Register for Storage of the Parity Error Flag
- **Package Options Include Plastic** Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

description

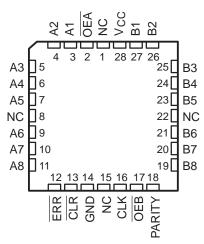
The 'ABT833 8-bit to 9-bit parity transceivers are designed for communication between data buses. When data is transmitted from the A bus to the B bus, a parity bit is generated. When data is transmitted from the B bus to the A bus with its corresponding parity bit, the open-collector parity-error (ERR) output indicates whether or not an error in the B data has occurred. The output-enable (OEA and OEB) inputs can be used to disable the device so that the buses are effectively isolated. The 'ABT833 provide true data at their outputs.

A 9-bit parity generator/checker generates a parity-odd (PARITY) output and monitors the parity of the I/O ports with the \overline{ERR} flag. \overline{ERR} is clocked into the register on the rising edge of the clock (CLK) input. The error flag register is cleared with a low pulse on the clear (CLR) input. When both OEA and OEB are low, data is transferred from the A bus to the B bus and inverted parity is generated. Inverted parity is a forced error condition that gives the designer more system diagnostic capability.

SN54ABT833 . . . JT PACKAGE SN74ABT833... DW OR NT PACKAGE (TOP VIEW)



SN54ABT833...FK PACKAGE (TOP VIEW)



NC - No internal connection



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EPIC-IIB is a trademark of Texas Instruments Incorporated



description (continued)

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

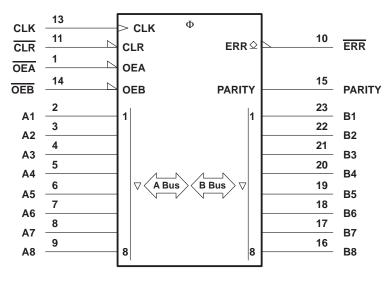
The SN54ABT833 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT833 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE

			INPUTS	3			OUTP	UT AND I/O		
OEB	OEA	CLR	CLK	$\begin{array}{c} \text{Ai} \\ \Sigma \text{ OF H's} \end{array}$	Bi† Σ OF H's	Α	В	PARITY	ERR‡	FUNCTION
L	Н	Х	Х	Odd Even	NA	NA	Α	L H	NA	A data to B bus and generate parity
Н	L	Н	Ť	NA	Odd Even	В	NA	NA	H L	B data to A bus and check parity
Х	Х	L	Х	Х	Х	Х	NA	NA	Н	Check error-flag register
н	н	H L H	No↑ No↑ ↑	X X Odd Even	Х	Z	Z	Z	NC H H L	Isolation§
L	L	Х	Х	Odd Even	NA	NA	Α	H L	NA	A data to B bus and generate inverted parity

NA = not applicable, NC = no change, X = don't care

logic symbol¶



[¶] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, JT, and NT packages.

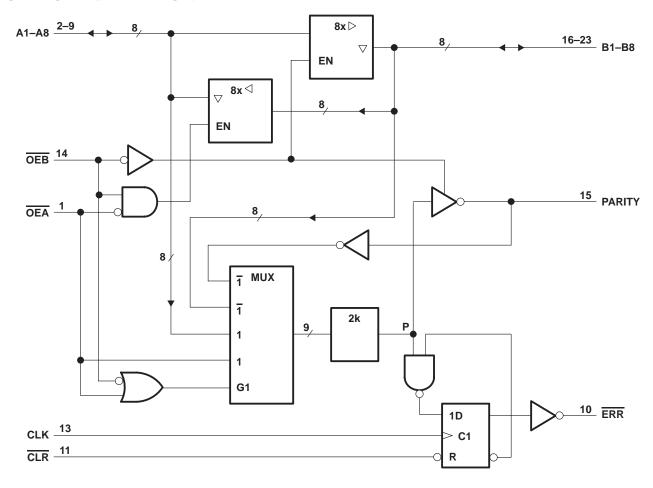


[†]Summation of high-level inputs includes PARITY along with Bi inputs.

[‡] Output states shown assume ERR was previously high.

[§] In this mode, ERR (when clocked) shows inverted parity of the A bus.

logic diagram (positive logic)



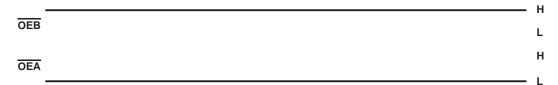
Pin numbers shown are for the DW, JT, and NT packages.

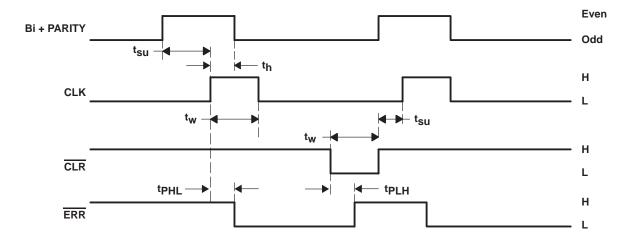
ERROR-FLAG FUNCTION TABLE

INP	UTS	INTERNAL TO DEVICE	OUTPUT PRE-STATE	OUTPUT ERR	FUNCTION
CLR	CLK	POINT P	ERR _{n-1} †	EKK	
Н	1	Н	Н	Н	
Н	\uparrow	X	L	L	Sample
Н	\uparrow	L	X	L	
L	L X X X		Н	Clear	

†The state of ERR before any changes at CLR, CLK, or point P

error-flag waveforms





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	\dots -0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	\dots -0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V _O	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT833	96 mA
SN74ABT833	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DW package	81°C/W
NT package	67°C/W
Storage temperature range, T _{stq}	. -65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.



recommended operating conditions (see Note 3)

			SN54AE	3T833	SN74A	3T833	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	h	2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage		0	Vcc	0	VCC	V
Vон	High-level output voltage	ERR	74	5.5		5.5	V
IOH	High-level output current	Except ERR	27/	-24		-32	mA
loL	Low-level output current		⁷ 0į	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Q	5		5	ns/V
TA	Operating free-air temperature		- 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CON	IDITIONS	T	A = 25°(;	SN54A	BT833	SN74A	BT833	UNIT	
PAI	RAWEIER	TEST CON	IDITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII	
VIK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
\ \ _{\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\}	All outputs	$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		v	
VOH	except ERR	V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$	2			2				V	
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2			
Vai		V _{CC} = 4.5 V	I _{OL} = 24 mA			0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	٧	
V _{hys}					100						mV	
ЮН	ERR	V _{CC} = 4.5 V,	V _{OH} = 5.5 V			20		20		20	μΑ	
ļ.,	Control inputs	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		#		±1	μA	
l II	A or B ports	vCC = 5.5 v,	AL = ACC OLGIAD			±100	00 ±100		±100	μΑ		
Ι _Ι L	A or B ports	$V_{CC} = 0$,	V _I = GND			-50		– 50		-50	μΑ	
loz _H ‡		V _{CC} = 5.5 V,	V _O = 2.7 V			50	<i></i>	50		50	μΑ	
l _{OZL} ‡		V _{CC} = 5.5 V,	V _O = 0.5 V			-50	22	-50		-50	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100	70,			±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50	Q	50		50	μΑ	
IO§		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-200¶	-50	-200¶	-50	-200¶	mA	
		V _{CC} = 5.5 V,	Outputs high		1	250		250		250	μΑ	
Icc	A or B ports	$I_{O} = 0$,	Outputs low		24	38¶		38¶		38¶	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250		250		250	μΑ	
	Data innuta	V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5	mA	
∆lcc#	Data inputs	Other inputs at V _{CC} or GND	Outputs disabled			50		50		50	μΑ	
	Control inputs	V _{CC} = 5.5 V, One inpu Other inputs at V _{CC} or				1.5		1.5		1.5	mA	
Ci	Control inputs	V _I = 2.5 V or 0.5 V			4.5						pF	
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V			10.5						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶] These limits may vary among suppliers.

[#]This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V _{CC} = T _A = 2	= 5 V, 25°C	SN54A	BT833	SN74A	BT833	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX		
t Dulas duratio	Pulse duration	CLK high or low			3 🖑		3		ns	
t _W	ruise duration	CLR low	3		3	35	3		113	
		B or PARITY high	9.8		9.8	ζ	9.8			
t _{su}	Setup time before CLK↑	B or PARITY low	8.1		8.1		8.1		ns	
		CLR	2		0 2		2			
th	Hold time after CLK↑	B or PARITY	0		0		0		ns	

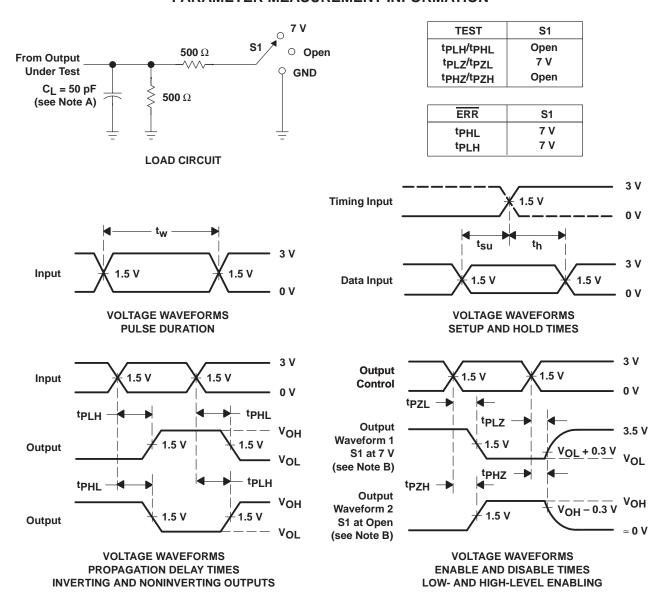
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT833		SN74ABT833		UNIT
	(INFOT)		MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
^t PLH	A or B	P.or A	1.2	2.8	4.8	1.2	5.4	1.2	5.3	no
t _{PHL}	AUIB	B or A	1	3	4.8‡	1	5.4	1	5.3‡	ns
^t PLH	А	PARITY	2.1	5.5	9.5	2.1	11.3	2.1	11.2	ns
^t PHL	A	FANITI	2.5	5.3	9.7	2.5	11,1	2.5	11	119
^t PZH	ŌĒ	PARITY	2.6	6.2	8.5	2.6	10.6	2.6	10.5	ns
t _{PZL}			2.6‡	5.8	8.6	2.6‡ <	10.1	2.6‡	10	110
^t PLH	CLR	ERR	1	3.2	4.8‡	(-)	5.3	1	5.2	no
^t PHL	CLK	EKK	1.2‡	2.8	5.7	1.2‡	6.3	1.2‡	6.2	ns
^t PZH		A, B, or PARITY	1	3.7	5.8‡	Q 1	6.6	1	6.5‡	
^t PZL	ŌĒ	A, B, OI PARII I	1.3‡	3.8	5.8	1.3‡	6.6	1.3‡	6.5‡	ns
^t PHZ	ŌĒ	A, B, or PARITY	1.9‡	4.4	7.3	1.9‡	8	1.9‡	7.9	
t _{PLZ}	OE .	A, B, OF PARITY	2.2‡	4.4	7.7	2.2‡	8.2	2.2‡	8.1	ns

 $[\]overline{\dagger}$ All typical values are at $V_{CC} = 5 \text{ V}$.

[‡]These limits may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_r \leq$ 2.5 ns, $t_f \leq$ 2.5 ns
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74ABT833DW	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT833
SN74ABT833DW.Z	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT833

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABT833DW	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74ABT833DW.Z	DW	SOIC	24	25	506.98	12.7	4826	6.6

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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